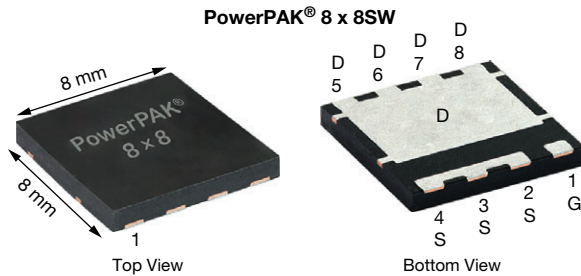


N-Channel 150 V (D-S) 175 °C MOSFET



FEATURES

- TrenchFET® Gen III power MOSFET
- Wettable flanks enhances solderability
- Fully lead (Pb)-free device
- Very low $R_{DS(on)}$
- Very low R_{thJC}
- PowerPAK® 8 x 8 with fuse lead to increase current density
- 100 % R_g and UIS tested
- Up to 161 A maximum continuous drain current
- Optimized safe operating area / SOA
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

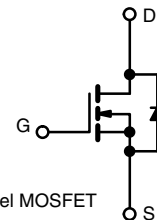


RoHS
COMPLIANT
HALOGEN
FREE

PRODUCT SUMMARY	
V_{DS} (V)	150
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 10$ V	0.0062
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 7.5$ V	0.0071
Q_g typ. (nC)	52
I_D (A) ^a	161
Configuration	Single

APPLICATIONS

- Hot swap
- Load switch
- Oring
- Motor drive
- Battery management



N-Channel MOSFET

ORDERING INFORMATION	
Package	PowerPAK® 8 x 8SW
Lead (Pb)-free and halogen-free	SiEH3716EW-T1-GE3

ABSOLUTE MAXIMUM RATINGS ($T_A = 25$ °C, unless otherwise noted)				
PARAMETER	SYMBOL	LIMIT	UNIT	
Drain-source voltage	V_{DS}	150	V	
Gate-source voltage	V_{GS}	± 20	V	
Continuous drain current ($T_J = 175$ °C)	I_D	$T_C = 25$ °C	161	A
		$T_C = 70$ °C	135	
		$T_A = 25$ °C	14.5 ^b	
		$T_A = 70$ °C	12.2 ^b	
Pulsed drain current ($V_{GS} = 10$ V, $t = 100$ μ s)	I_{DM}	500	A	
Continuous source-drain diode current	I_S	$T_C = 25$ °C	379	A
		$T_A = 25$ °C	3.1 ^b	
Single pulse avalanche current	I_{AS}	79	A	
Single pulse avalanche energy	E_{AS}	310	mJ	
Maximum power dissipation	P_D	$T_C = 25$ °C	417	W
		$T_C = 70$ °C	292	
		$T_A = 25$ °C	3.4 ^b	
		$T_A = 70$ °C	2.4 ^b	
Operating junction and storage temperature range	T_J, T_{stg}	-55 to +175	°C	
Soldering recommendations (peak temperature) ^c		260	°C	

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYPICAL	MAXIMUM	UNIT	
Maximum junction-to-ambient ^b	R_{thJA}	33	44	°C/W	
Maximum junction-to-case (drain)	R_{thJC}	0.27	0.36	°C/W	

Notes

- $T_C = 25$ °C
- Surface mounted on 1" x 1" FR4 board
- See solder profile (www.vishay.com/doc?73257). The PowerPAK 8 x 8L is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- Rework conditions: manual soldering with a soldering iron is not recommended for leadless components



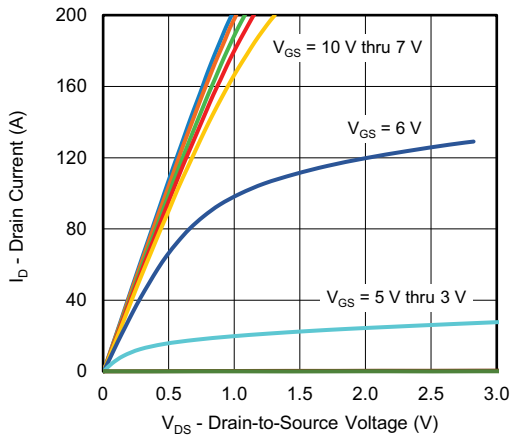
SPECIFICATIONS ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static						
Drain-source breakdown voltage	V_{DS}	$V_{GS} = 0\text{ V}$, $I_D = 250\text{ }\mu\text{A}$	150	-	-	V
V_{DS} temperature coefficient	$\Delta V_{DS}/T_J$	$I_D = 10\text{ mA}$	-	117	-	mV/ $^\circ\text{C}$
$V_{GS(th)}$ temperature coefficient	$\Delta V_{GS(th)}/T_J$	$I_D = 250\text{ }\mu\text{A}$	-	-9.5	-	
Gate-source threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$, $I_D = 250\text{ }\mu\text{A}$	2	-	5	V
Gate-source leakage	I_{GSS}	$V_{DS} = 0\text{ V}$, $V_{GS} = \pm 20$	-	-	± 100	nA
Zero gate voltage drain current	I_{DSS}	$V_{DS} = 150\text{ V}$, $V_{GS} = 0\text{ V}$	-	-	1	μA
		$V_{DS} = 150\text{ V}$, $V_{GS} = 0\text{ V}$, $T_J = 70\text{ }^\circ\text{C}$	-	-	15	
Drain-source on-state resistance ^a	$R_{DS(on)}$	$V_{GS} = 10\text{ V}$, $I_D = 15\text{ A}$	-	0.0049	0.0062	Ω
		$V_{GS} = 7.5\text{ V}$, $I_D = 15\text{ A}$	-	0.0054	0.0071	
Forward transconductance ^a	g_{fs}	$V_{DS} = 15\text{ V}$, $I_D = 50\text{ A}$	-	88	-	S
Dynamic ^b						
Input capacitance	C_{iss}	$V_{DS} = 75\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 1\text{ MHz}$	-	3660	-	pF
Output capacitance	C_{oss}		-	705	-	
Reverse transfer capacitance	C_{rss}		-	14	-	
Total gate charge	Q_g	$V_{DS} = 75\text{ V}$, $V_{GS} = 10\text{ V}$, $I_D = 15\text{ A}$	-	67	100	nC
		$V_{DS} = 75\text{ V}$, $V_{GS} = 7.5\text{ V}$, $I_D = 15\text{ A}$	-	52	78	
Gate-source charge	Q_{gs}		-	19	-	
Gate-drain charge	Q_{gd}		-	17.3	-	
Gate resistance	R_g	$f = 1\text{ MHz}$	1.1	5.5	11	Ω
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 75\text{ V}$, $R_L = 7.5\text{ }\Omega$, $I_D \cong 10\text{ A}$, $V_{GEN} = 10\text{ V}$, $R_g = 1\text{ }\Omega$	-	13	30	ns
Rise time	t_r		-	8	15	
Turn-off delay time	$t_{d(off)}$		-	60	120	
Fall time	t_f		-	22	45	
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 75\text{ V}$, $R_L = 7.5\text{ }\Omega$, $I_D \cong 10\text{ A}$, $V_{GEN} = 7.5\text{ V}$, $R_g = 1\text{ }\Omega$	-	17	35	
Rise time	t_r		-	52	105	
Turn-off delay time	$t_{d(off)}$		-	48	100	
Fall time	t_f		-	22	45	
Drain-Source Body Diode Characteristics						
Continuous source-drain diode current	I_S	$T_C = 25\text{ }^\circ\text{C}$	-	-	379	A
Pulse diode forward current	I_{SM}		-	-	500	
Body diode voltage	V_{SD}	$I_S = 10\text{ A}$, $V_{GS} = 0\text{ V}$	-	0.70	1.1	V
Body diode reverse recovery time	t_{rr}	$I_F = 10\text{ A}$, $di/dt = 100\text{ A}/\mu\text{s}$, $T_J = 25\text{ }^\circ\text{C}$	-	100	200	ns
Body diode reverse recovery charge	Q_{rr}		-	420	840	nC
Reverse recovery fall time	t_a		-	75	-	ns
Reverse recovery rise time	t_b		-	25	-	

Notes

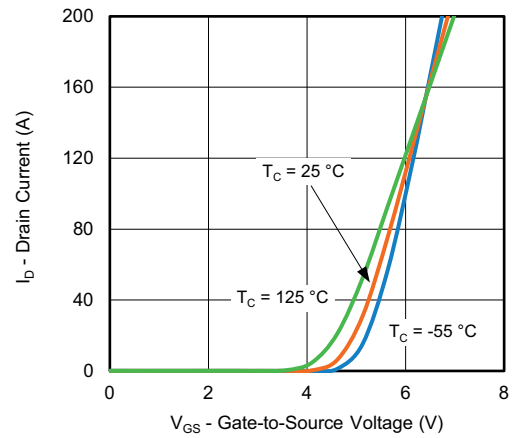
- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$
b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

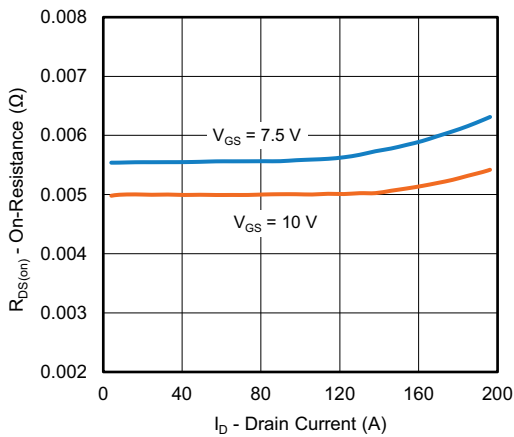
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



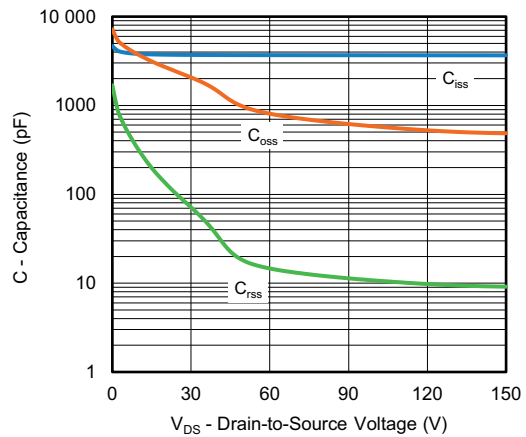
Output Characteristics



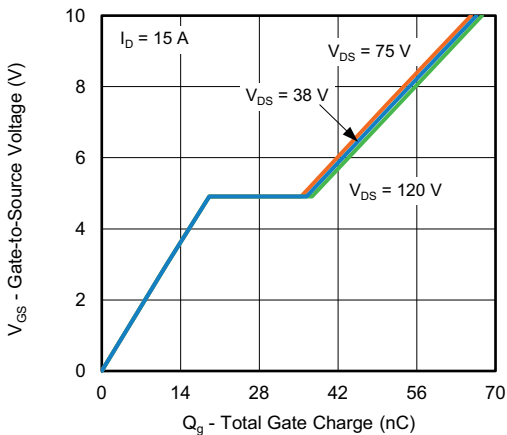
Transfer Characteristics



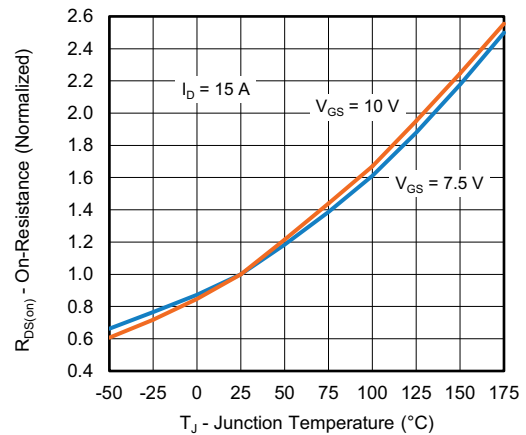
On-Resistance vs. Drain Current and Gate Voltage



Capacitance



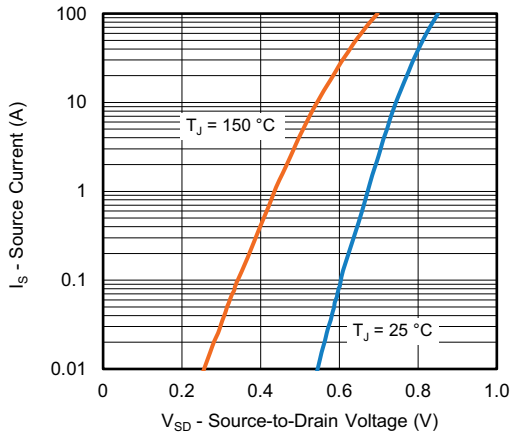
Gate Charge



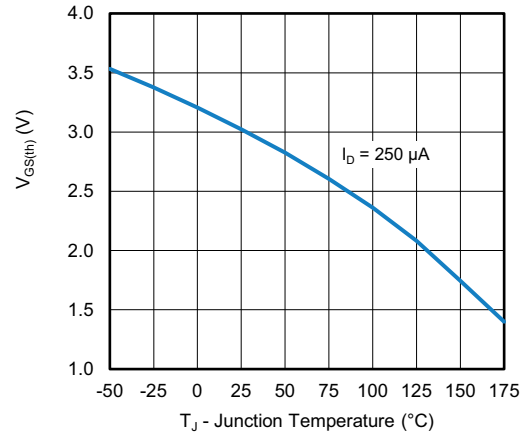
On-Resistance vs. Junction Temperature



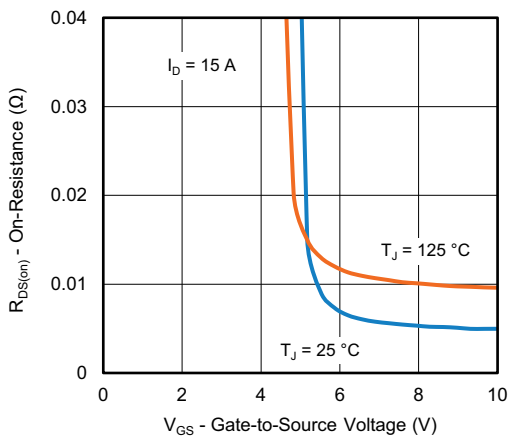
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



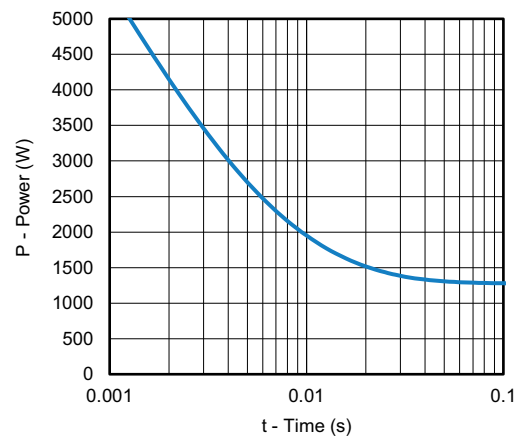
Source-Drain Diode Forward Voltage



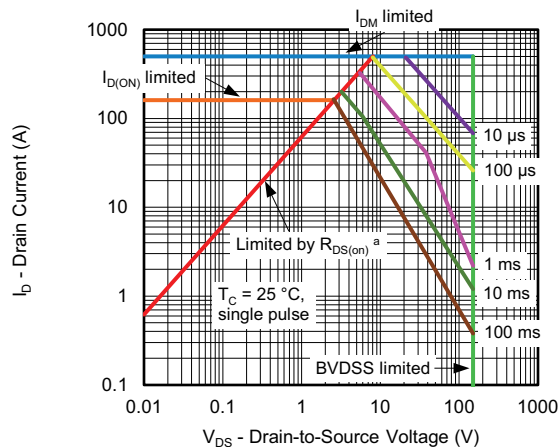
Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power, Junction-to-Case



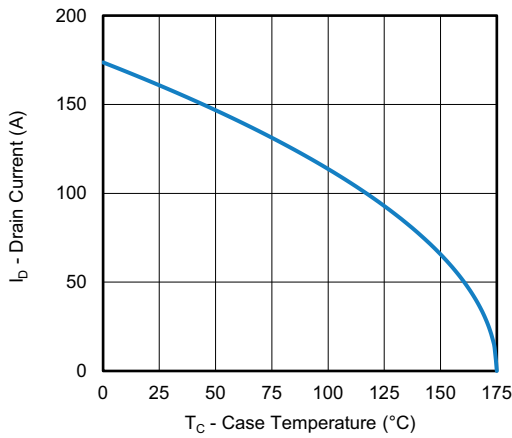
Safe Operating Area, Junction-to-Case

Note

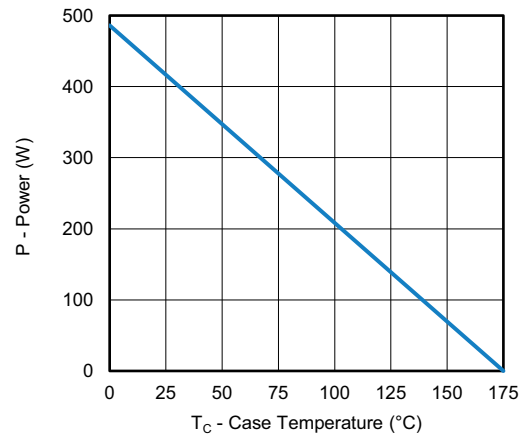
a. $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Current Derating ^a



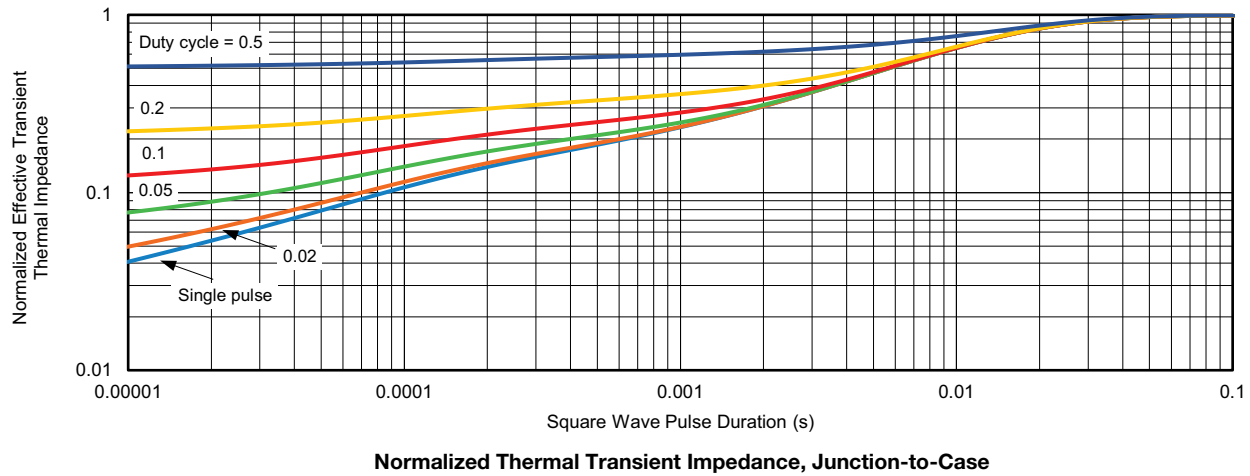
Power, Junction-to-Case

Note

- a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



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